

WHAT IS CLAIMED:

1 1. A method for electrically coupling together at least two electrically conductive
 2 layers of a printed circuit board, the method comprising the steps of:
 3 forming at least one through-hole in the printed circuit board; and
 4 inserting in the at-least-one through-hole an electrically conductive stake for
 5 electrically coupling foils disposed on the at least two electrically conductive layers
 6 together.

1 2. The method of claim 1 wherein the conductive stake has a polygonal shape,
 2 and the inserting step inserts the conductive stake such that at least one point of the
 3 polygonal shape makes contact with the foils.

1 3. The method of claim 1 wherein the conductive stake has conductive fins
 2 attached along a length of the conductive stake, and the inserting step inserts the
 3 conductive stake such that at least one conductive fin makes contact with the foils.

1 4. The method of claim 1 wherein the inserting step inserts the conductive stake
 2 such that the conductive stake is substantially disposed within the printed circuit board.

1 5. The method of claim 1 wherein the inserting step inserts the conductive stake
 2 such that a portion of the conductive stake extends beyond a surface of the printed circuit
 3 board.

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 1 6. A printed circuit board comprising:
 2 at least three layers of material, such that two of the layers of material are
 3 electrically conductive and the third layer is an electrical insulator and wherein the
 4 insulating layer is disposed between the conductive layers; and
 5 at least one conductive stake inserted into the printed circuit board for forming a
 6 via for electrically connecting foils from the two conductive layers together.

1 7. The printed circuit board of claim 6 wherein the conductive stake has a
 2 polygonal shape and is inserted such that at least one point of the polygonal shape makes

3 contact with the foils for forming the via.

1 8. The printed circuit board of claim 6 wherein the conductive stake has
2 conductive fins attached along a length of the conductive stake, and is inserted such that
3 at least one conductive fin makes contact with the foils for forming the via.

1 9. The printed circuit board of claim 6 wherein the conductive stake is
2 substantially disposed within the printed circuit board.

1 10. The printed circuit board of claim 6 wherein a portion of the conductive stake
2 extends beyond a surface of the printed circuit board.

Sub 1 11. A printed circuit board comprising:
2 at least four conductive layers of material; and
3 at least two conductive stakes inserted into a through hole of the printed circuit
4 board for forming at least two different vias, one via electrically connecting together foils
5 from two of the four conductive layers and the other via electrically connecting together
6 foils from the remaining two of the four conductive layers.

1 12. The printed circuit board of claim 11 wherein at least one conductive stake
2 has a polygonal shape, and is inserted such that at least one point of the polygonal shape
3 makes contact with foils from two of the four conductive layers.

1 13. The printed circuit board of claim 11 wherein at least one conductive stake has
2 conductive fins attached along a length of the conductive stake, and is inserted such that
3 at least one conductive fin makes contact with foils from two of the four conductive
4 layers.

1 14. The printed circuit board of claim 11 wherein at least one of the conductive
2 stakes is substantially disposed within the printed circuit board.

1 15. The printed circuit board of claim 11 wherein a portion of at least one of the
2 conductive stakes extends beyond a surface of the printed circuit board.